



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

For: INSULATED BOND WIRE ASSEMBLY
PROCESS TECHNOLOGY FOR
INTEGRATED CIRCUITS

Art Unit: 2826

AMENDMENT

In response to the Office Action mailed November 20, 2003, please amend the above-
 ied application as follows.

Remarks/Arguments begin on page 6 of this paper.

Signature

Date _____